



P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
- 20	0.00875 at $V_{GS} = - 4.5$ V	- 14
	0.01075 at $V_{GS} = - 2.5$ V	- 12
	0.0135 at $V_{GS} = - 1.8$ V	- 11

FEATURES

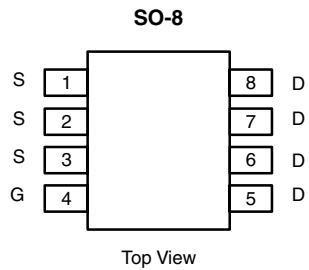
- TrenchFET[®] Power MOSFET

APPLICATIONS

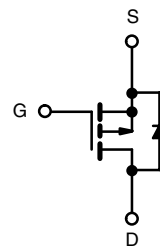
- Game Station
- Load Switch



RoHS*
COMPLIANT



Ordering Information: Si4421DY-T1
Si4421DY-T1-E3 (Lead (Pb)-free)



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted				
Parameter	Symbol	10 secs	Steady State	Unit
Drain-Source Voltage	V_{DS}	- 20		V
Gate-Source Voltage	V_{GS}	± 8		
Continuous Drain Current ($T_J = 150$ °C) ^a	I_D	$T_A = 25$ °C	- 14	- 10
		$T_A = 70$ °C	- 11.5	- 8
Pulsed Drain Current	I_{DM}	- 40		A
Continuous Source Current (Diode Conduction) ^a	I_S	- 2.7	- 1.36	
Maximum Power Dissipation ^a	P_D	$T_A = 25$ °C	3.0	1.5
		$T_A = 70$ °C	1.9	0.95
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	R_{thJA}	$t \leq 10$ sec	33	42	°C/W
		Steady State	70	85	
Maximum Junction-to-Foot (Drain)	R_{thJF}	16	21		

Notes:

a. Surface Mounted on 1" x 1" FR4 Board.

* Pb containing terminations are not RoHS compliant, exemptions may apply.



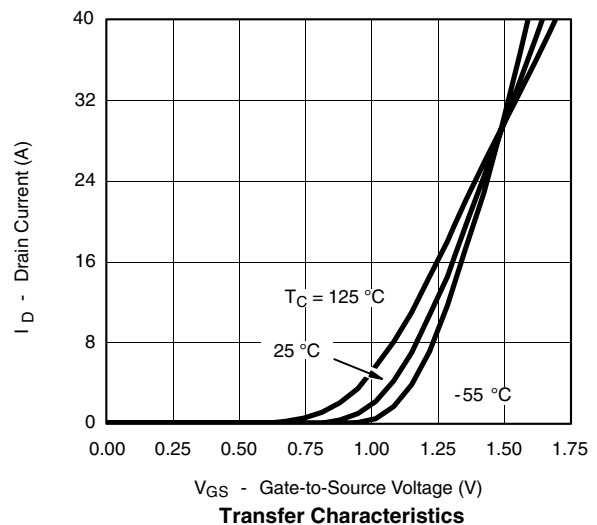
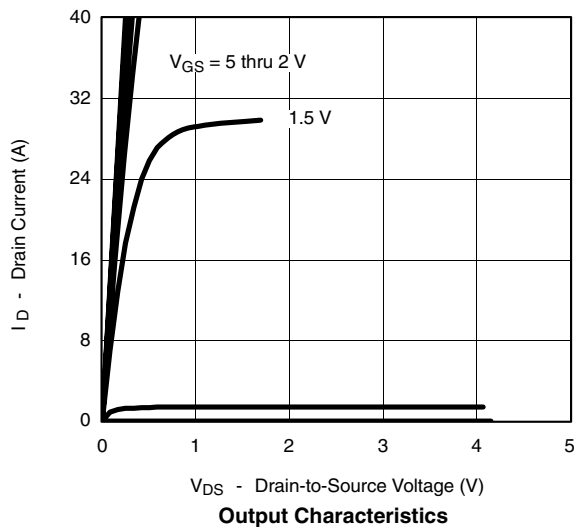
SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -850\text{ }\mu\text{A}$	-0.4		-0.8	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 8\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$			-1	μA
		$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}, T_J = 70\text{ }^\circ\text{C}$			-10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} = -5\text{ V}, V_{GS} = -4.5\text{ V}$	-30			A
Drain-Source On-State Resistance ^a	$r_{DS(on)}$	$V_{GS} = -4.5\text{ V}, I_D = -14\text{ A}$		0.007	0.00875	Ω
		$V_{GS} = -2.5\text{ V}, I_D = -12\text{ A}$		0.0085	0.01075	
		$V_{GS} = -1.8\text{ V}, I_D = -11\text{ A}$		0.011	0.0135	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10\text{ V}, I_D = -14\text{ A}$		55		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -2.7\text{ A}, V_{GS} = 0\text{ V}$		-0.6	-1.1	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -10\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -14\text{ A}$		82	125	nC
Gate-Source Charge	Q_{gs}		10			
Gate-Drain Charge	Q_{gd}		27			
Gate Resistance	R_g			3		Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10\text{ V}, R_L = 10\text{ }\Omega$ $I_D \cong -1\text{ A}, V_{GEN} = -4.5\text{ V}, R_G = 6\text{ }\Omega$		45	70	ns
Rise Time	t_r		90	140		
Turn-Off Delay Time	$t_{d(off)}$		350	550		
Fall Time	t_f		170	260		
Source-Drain Reverse Recovery Time	t_{rr}		$I_F = -2.1\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$		135	

Notes:

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.

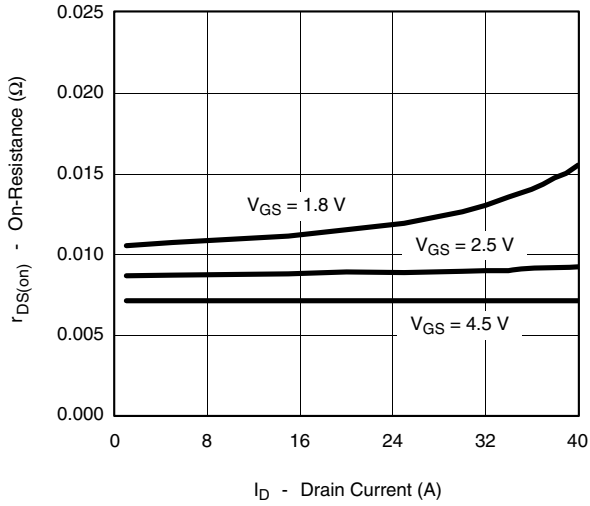
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS $25\text{ }^\circ\text{C}$, unless otherwise noted

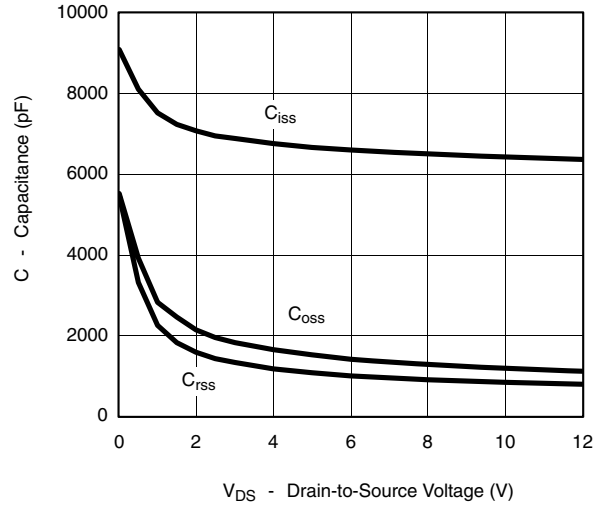




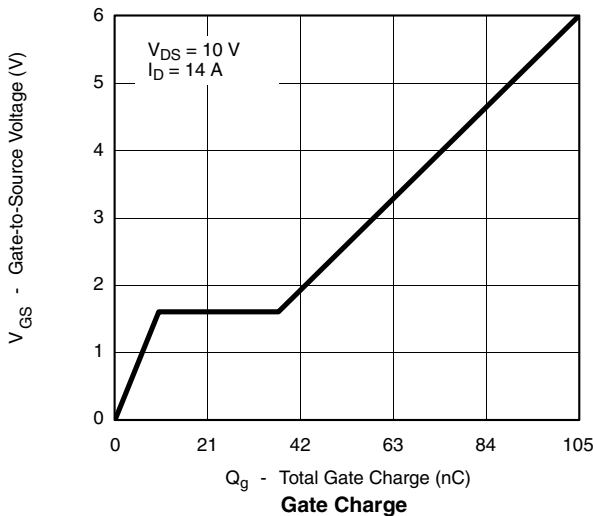
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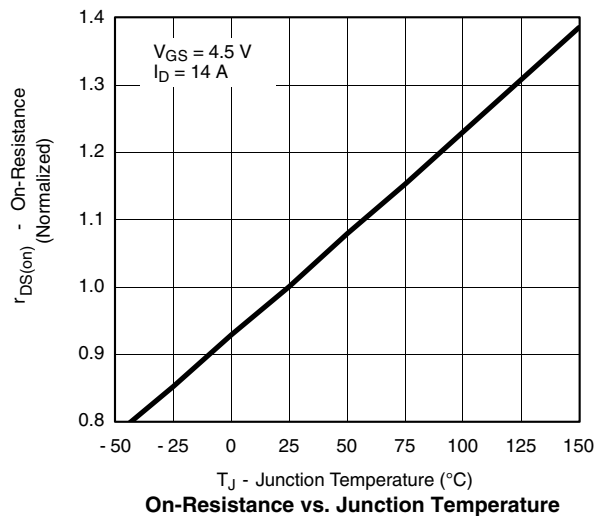
On-Resistance vs. Drain Current



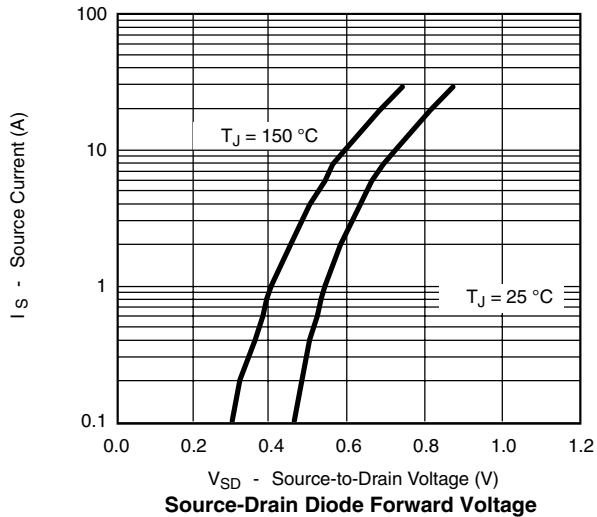
Capacitance



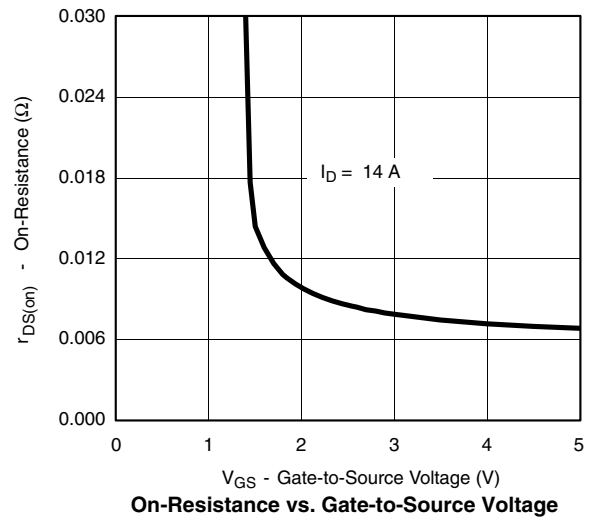
Gate Charge



On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



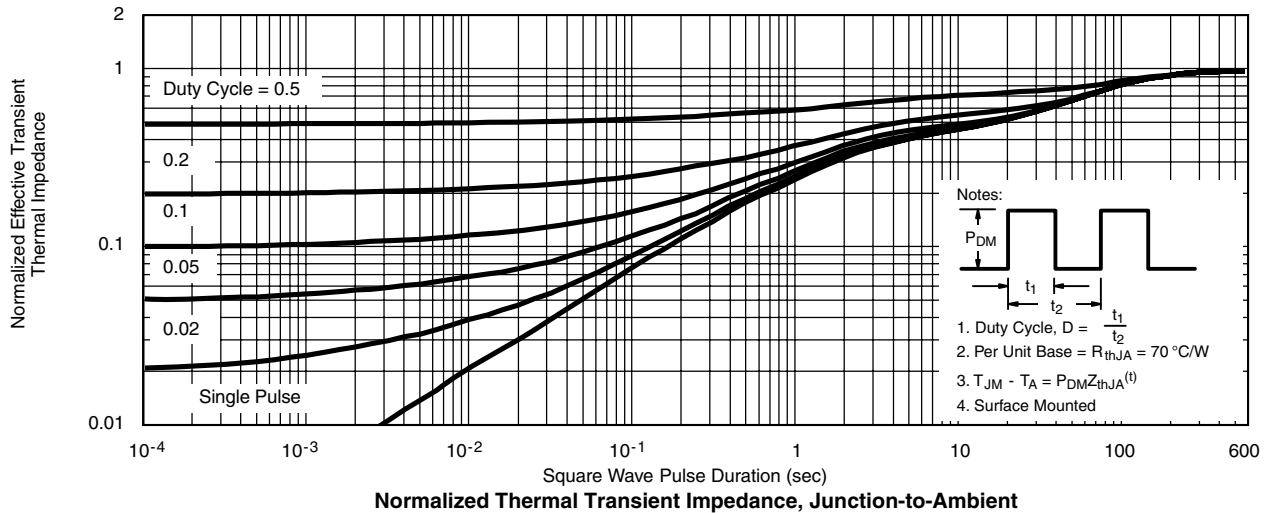
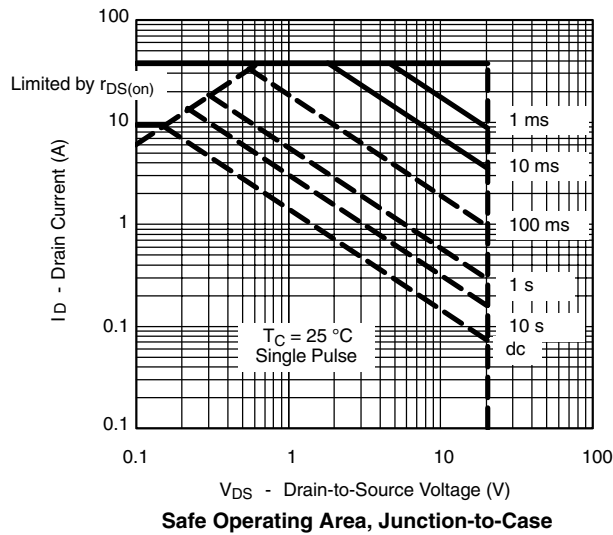
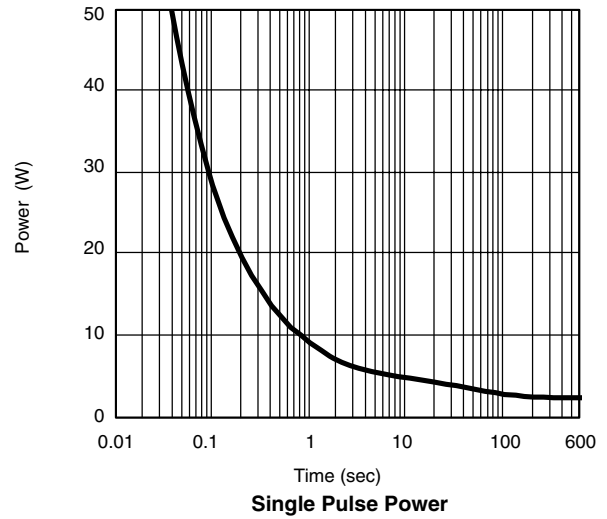
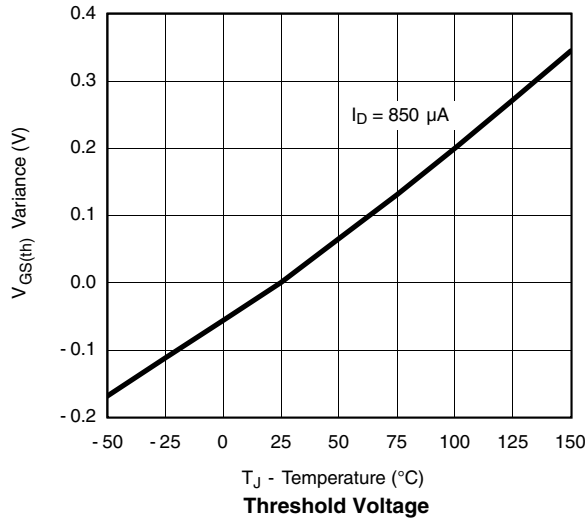
On-Resistance vs. Gate-to-Source Voltage

Si4421DY

Vishay Siliconix

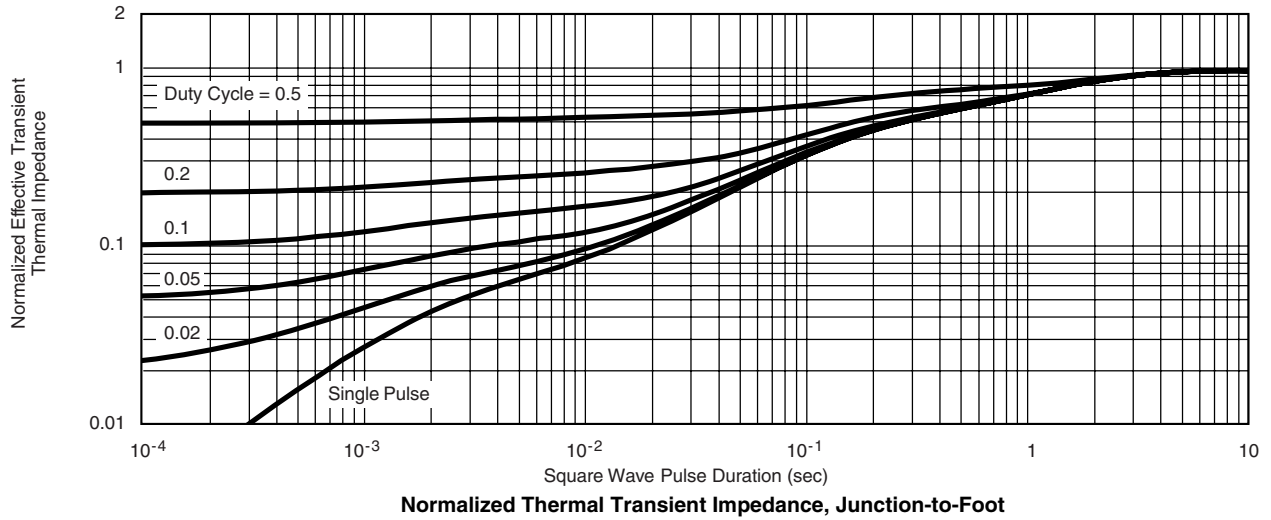


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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